

Housing wall e.g. for data processor housing, comprises non overlapping recesses in two transparent plates

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Equivalents:

Abstract

The housing wall for a housing (6) has a first plate or panel (1) and a second plate or panel (2). The panels are preferably transparent and are spaced apart one behind the other. Each plate has several recesses (4,5).

The panels are arranged such that the recesses (4) of the first panel (1) do not overlap with those (5) of the second panel (2).